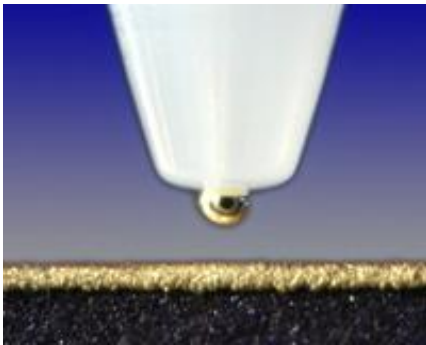


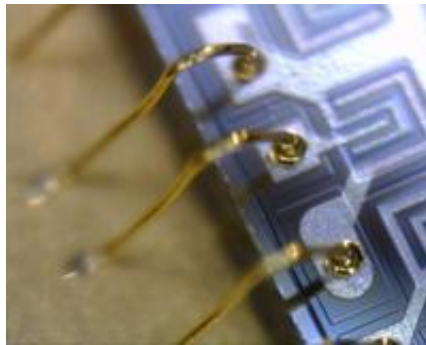
TPT-application standard 25 μ gold ball-wedge bonding

Equipment:

- 25 μ gold wire, 100m at 2" spool
- Standard 25 μ capillary
- Semiautomatic Ball-Wedge Wire Bonder HB16



capillary



ball bonding



ball bond

Bonding process:

- thread wire to the capillary.
- program bond parameters, ball size and loop profile.
- after second bond clamp is closes, wire is cut and ball is made by EFO (electronic flame off).
- it is recommended to heat up bond surface up to 120°C.

Advantages over wedge-wedge bonding:

- First bond connection more stable.
- Bonding may softer.
- The wire move vertically, that good for big height difference.
- Gold and copper wire possible.

